

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/11/2022

Details for "TPS628110AQWRWYRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS628110AQWRWYRQ1	NIPDAU	Level-2-260C-1 YEAR	TI Semiconductor	RWY   9	3x2x0.9	14

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	5.367175	97.585	975850	38.281787	382818
Copper and Its Alloys	Iron	7439-89-6	0.1265	2.3	23000	0.902271	9023
Copper and Its Alloys	Phosphorus	7723-14-0	0.000825	0.015	150	0.005884	59
Zinc and Its Alloys	Zinc	7440-66-6	0.0055	0.1	1000	0.039229	392
Sub-Total			5.5	100	1000000	39.229171	392292
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.041853	95.120455	951205	0.29852	2985
Precious Metals	Gold	7440-57-5	0.000343	0.779545	7795	0.002446	24
Precious Metals	Palladium	7440-05-3	0.001804	4.1	41000	0.012867	129
Sub-Total			0.044	100	1000000	0.313833	3138
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	6.214607	87.999993	880000	44.32616	443262
Other Organic Materials	Chlorine	7782-50-5	0.000071	0.001005	10	0.000506	5
Other Plastics and Rubber	Carbon Black	1333-86-4	0.021186	0.299998	3000	0.151111	1511
Thermoplastics	Epoxy	85954-11-6	0.82619	11.699004	116990	5.892863	58929
Sub-Total			7.062054	100	1000000	50.370641	503706
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	1.312291	100	1000000	9.360016	93600
Sub-Total			1.312291	100	1000000	9.360016	93600
<b>Solder Bump</b>							
Copper and Its Alloys	Copper	7440-50-8	0.089736	88.119881	881199	0.640049	6400
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.011487	11.280123	112801	0.081932	819
Precious Metals	Silver	7440-22-4	0.000611	0.599996	6000	0.004358	44
Sub-Total			0.101834	100	1000000	0.726339	7263
<b>Total</b>			14.020179			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."  
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/eoinfo](http://www.ti.com/eoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.